SCIENTECH

(3583)

2019/6/13

Safe Harbor Statement

- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

Scientech Corp (3583: TT)

Company Establishment	1979/10/17
IPO	2013/3/12
Capital	NT$ 811 Million
Chairman	H.L. Hsieh
President	M.T. Hus
Products	Equipment Manufacturing、Wafer Reclaim、Trading(Agent/Distributor)

Business Overviews

Products

Future Prospect

Business Overview

Income Statement

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Units：NT $ M	2014	2015	2016	2017	2018	1Q19
Revenues	2,717	2,942	3,495	3,539	3,988	1,048
Gross Profit	970	903	1,178	1,251	1,448	353
Operating Expenses	673	779	835	829	935	227
Operating Income	297	124	343	423	514	126
Other Income and Expenses	20	(6)	21	(8)	26	3
Income Before Tax	317	119	363	415	540	129
Net Income	246	86	292	328	418	95
EPS	3.04	1.06	3.60	4.05	5.16	1.18
Gross Margin	35.71%	30.69%	33.71%	35.36%	36.32%	33.63%
Operating Margin	10.93%	4.23%	9.80%	11.95%	12.89%	11.98%
Income Before Tax margin	11.68%	4.03%	10.40%	11.72%	13.54%	12.32%

Business Overview

Products Mix

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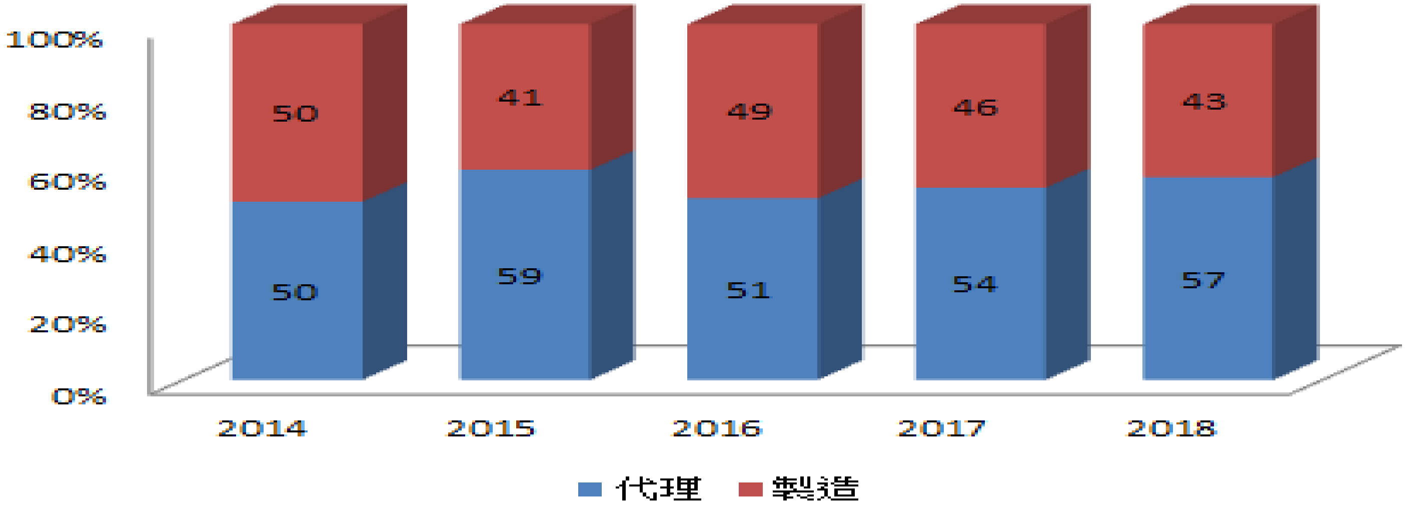
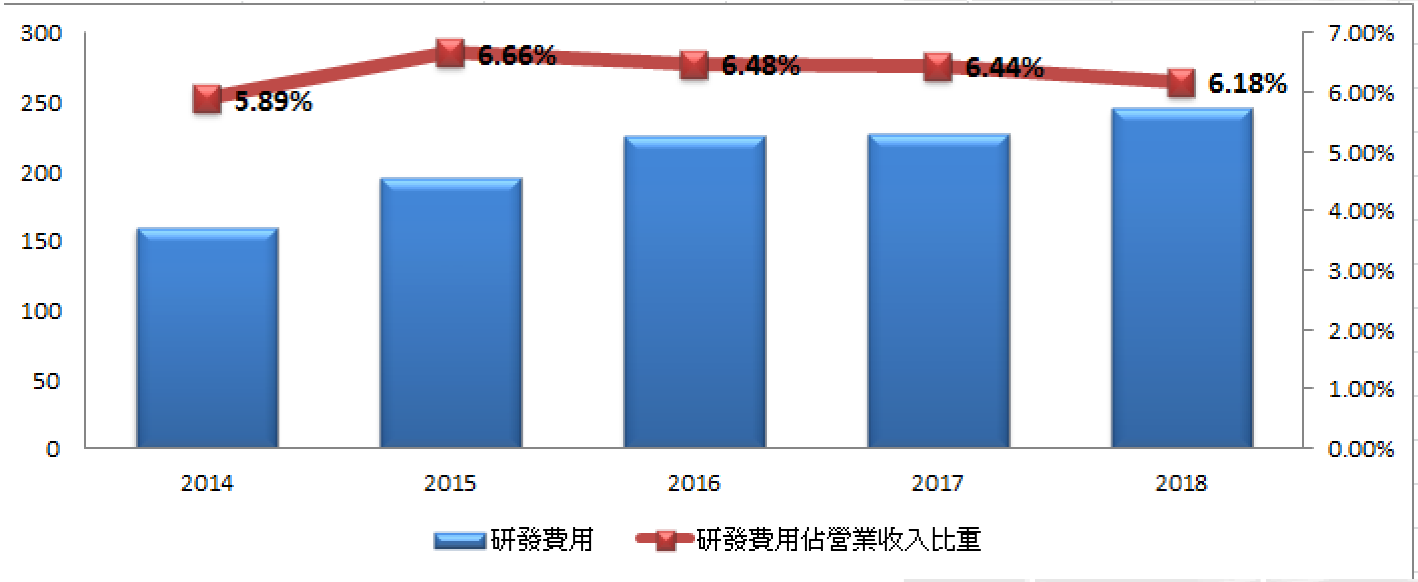
Units：%	2014	2015	2016	2017	2018	Gross Margin
Trading	50	59	51	54	57	Below Average
Manufacturing	50	41	49	46	43	Above Average

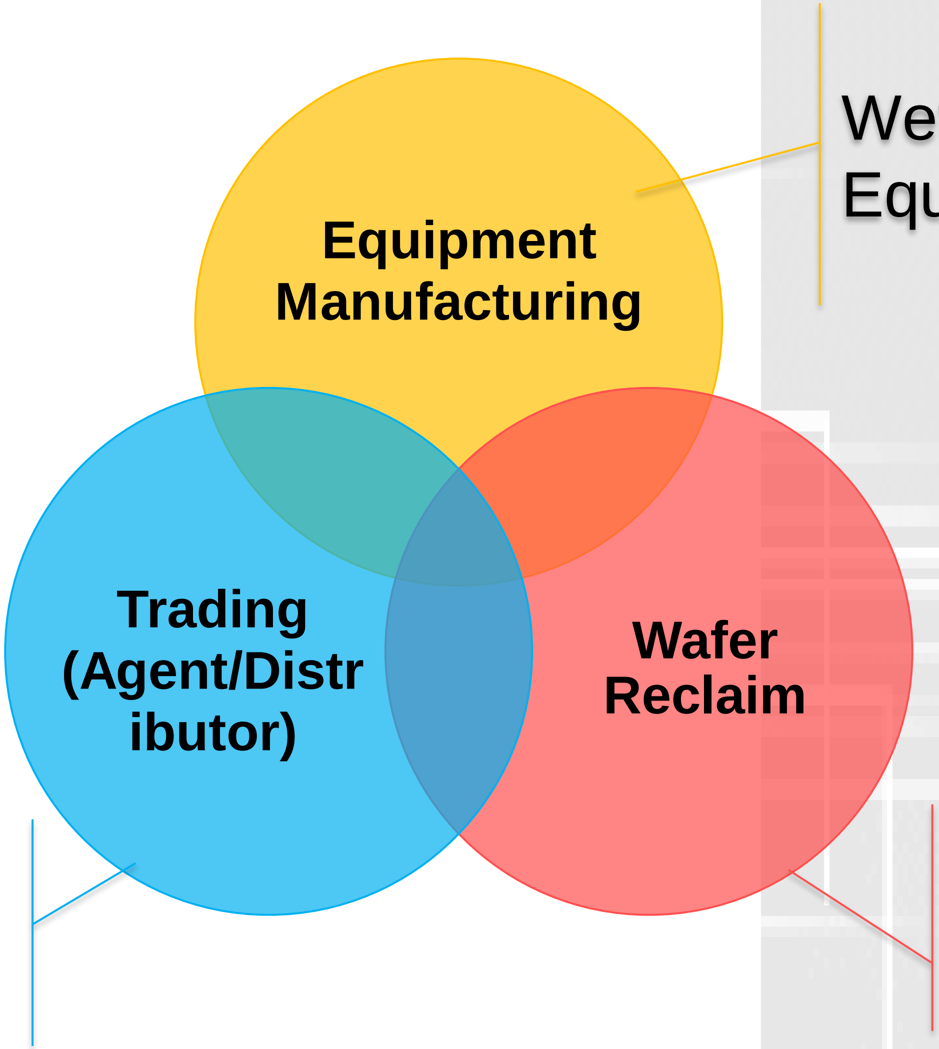


R&D Expenses

Units：NT $ M	2014	2015	2016	2017	2018
R&D Expenses	160	196	226	228	246
Expenses as % of Revenue	5.89%	6.66%	6.48%	6.44%	6.18%



Products



Equipment Manufacturing

Trading (Agent/Distributor)

Wafer Reclaim

Wet Process Equipment

Semiconductor and
Optoelectronics
Process Equipment

12” Wafer Reclaim

Products

Equipment Manufacturing

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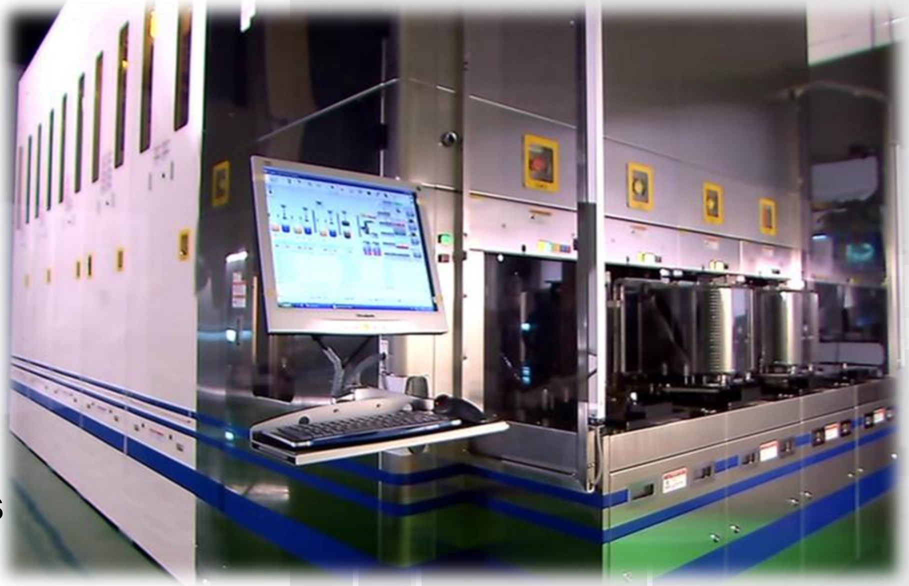
Wet process equipment

- **Single wafer/ Batch type**
  - **8”/12’ Advanced packaging**

    (Fan-out、 Solder Bump、Copper Pillow 、Bumping 、Gold Bump 、 RDL 、 TSV …ect)
  - **6”/ 8”/12” Front-end special process** (IoT Sensor 、 Power IC FP sensor、RF、CMOS、Touch Controller、 MEMS)
  - **HB LED fully-automatic process**
  - **MEMS**
  - **III-V**



Products

Si Wafer Reclaim

- 12” Wafer Reclaim
- Capacity: 120K / month
- Separated Cu & Non Cu Line

Advanced clean technology
- **20nm/ 16nm Particle**
- **Low trace metal (<5E9)**

Complete particle inspection (SP1-DLS & SP2)

Complete polishing process
- **Single side polish**
- **Double side polish**
- **Final Haze polish**

Super flatness (GBIR<0.5μm)

Trading (Agent/Distributor)

Multi application

Exclusive Agency

Supply Chain Partnership

ExOne DIGITAL PART MATERIALIZATION

ReVera

RAVE

ECO-SNOW SYSTEMS

POONGSAN MICROTEC

Canon

xradia insight in 3D

FerroTec

ADVANCED ENERGY

Hirata

Plasma-Therm

KLA Tencor Already there

USHIO

UCP PLASMA TECHNOLOGIES

e2

RUDOLPH RESEARCH ANALYTICAL

VLSI Standards Incorporated

タカノ株式会社

FRT

AYUMI INDUSTRY CO.,LTD. Ayumi アユミ工業株式会社

NAKAN

Kensington LABORATORIES

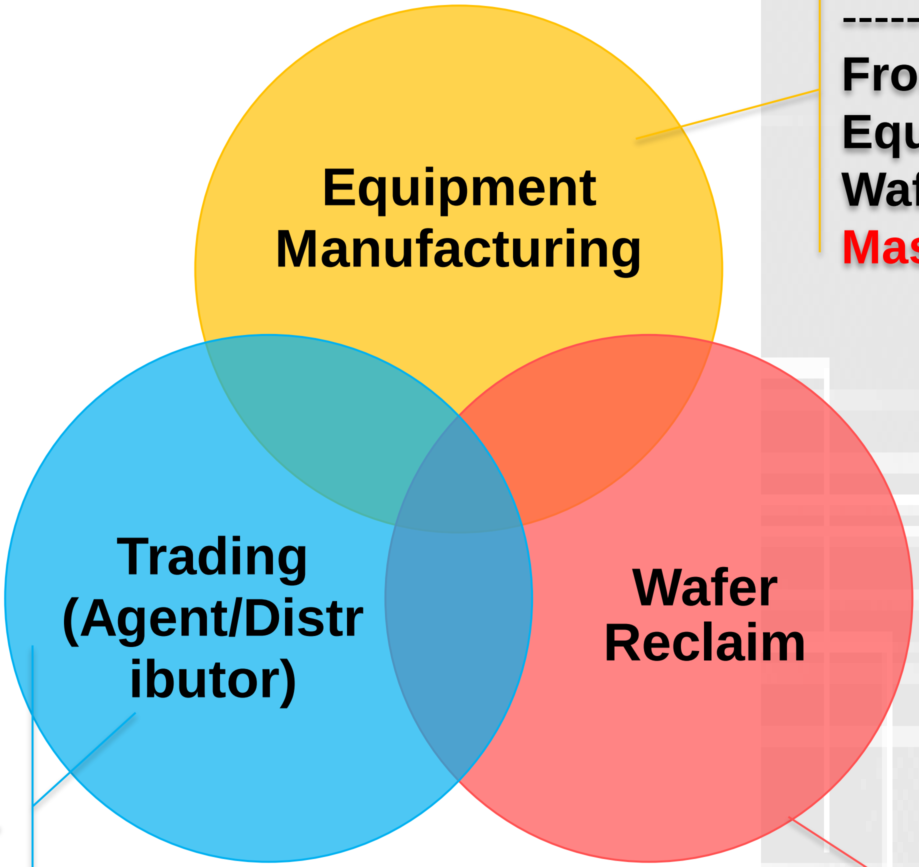
Verity INSTRUMENTS, INC.

OAI

NST [주]엔에스티 NST INC.

Future Prospect

Product-based Extension



Equipment Manufacturing

Trading (Agent/Distributor)

Wafer Reclaim

Wet Process Equipment

Front-end Wet Process Equipment
Wafer Support System
Mass Spectrometer

Semiconductor and Optoelectronics Process Equipment

AMOLED
Advanced Process Miniaturization

12" Wafer Reclaim

SiC Wafer Reclaim

Q & A

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Thank You!